

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	11	("5653575" "5765277" "6012502").PN. OR ("6742561").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 13:26
L2	26	("3604108" "5197650" "5516026" "5579980").PN. OR ("5765277").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 13:26
L3	10	(L1 L2) and (cure curing cured)	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 13:26
L4	26	("3604108" "5197650" "5516026" "5579980").PN. OR ("5765277").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 13:44
L5	2308	("156" "414" "438" "29").clas. and (((carrier backing tape) same (photopattern\$4 etch\$3 photocur\$4) same (die circuit chip))	US-PGPUB; USPAT	OR	ON	2007/04/18 14:38
L7	633	("156" "414" "438" "29").clas. and (((carrier backing tape) same (photopattern\$4 etch\$3 photocur\$4) same (die circuit chip) same substrate) and (vias via)	US-PGPUB; USPAT	OR	ON	2007/04/18 13:56
L8	233	("156" "414" "438" "29").clas. and (((carrier backing tape) with (photopattern\$4 etch\$3 photocur\$4)) same (die circuit chip) same substrate) and (vias via)	US-PGPUB; USPAT	OR	ON	2007/04/18 13:58
L9	349	("156" "414" "438" "29").clas. and (((carrier backing tape) with (photopattern\$4 expos\$3 photocur\$4)) same (die circuit chip) same substrate) and (vias via)	US-PGPUB; USPAT	OR	ON	2007/04/18 14:02
L10	4	("156" "414" "438" "29").clas. and (((carrier backing tape) with (photopattern\$4 photo-pattern\$4 photo-cur\$4 photocur\$4)) same (die circuit chip) same substrate) and (vias via)	US-PGPUB; USPAT	OR	ON	2007/04/18 14:03
L11	23	("156" "414" "438" "29").clas. and (((carrier backing tape) same (photopattern\$4 photo-pattern\$4 photo-cur\$4 photocur\$4)) same (die circuit chip) same substrate) and (vias via)	US-PGPUB; USPAT	OR	ON	2007/04/18 14:12

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L12	6	("156" "414" "438" "29").clas. and (((carrier backing liner lining) same (photopattern\$4 photo-pattern\$4 photo-cur\$4 photocur\$4)) same (die circuit chip) same (peel\$4 remov\$4)) and (vias via)	US-PGPUB; USPAT	OR	ON	2007/04/18 14:28
L13	45	("4630096" "4746960" "4827328" "4860166" "4866508" "4878991" "4884122" "4894115" "4907062" "4933042" "5049980" "5091769" "5111278" "5144747" "5250843" "5324687" "5426566" "5757072").PN. OR ("6159767"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 14:16
L14	87	(((carrier backing liner lining) with (photopattern\$4 photo-pattern\$4 photo-cur\$4 photocur\$4)) same (die circuit chip) same (peel\$4 remov\$4)) and (vias via)	US-PGPUB; USPAT	OR	ON	2007/04/18 14:28
L15	538	("156" "414" "438" "29").clas. and ((transfer\$4) same (die circuit chip) same adhesive same coat\$4)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:14
L16	67	("156" "414" "438" "29").clas. and ((transfer\$4) same (die circuit chip) same adhesive same (deposit\$4 coat\$4) same (via vias))	US-PGPUB; USPAT	OR	ON	2007/04/18 14:58
L17	86	("156" "414" "438" "29").clas. and ((transfer\$4) same (die circuit chip) same adhesive same (deposit\$4 coat\$4)) and apparatus.ab.	US-PGPUB; USPAT	OR	ON	2007/04/18 17:47
L18	17	("3785507" "4472218" "4526646" "4724030" "4797994" "4915565" "4990051" "5098501" "5270260" "5589029" "5725728" "5827394" "5871610" "6039833").PN. OR ("6248201"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 15:07
L19	200	("156" "414" "438" "29").clas. and ((transfer\$4) same (die circuit chip) same vibrat\$4)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:14
L20	24	("156" "414" "438" "29").clas. and ((transfer\$4) same (die circuit chip) same vibrat\$4 same remov\$4)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:19
L21	29	("156" "414" "438" "29").clas. and ((transfer\$4) same (die circuit chip) same vibrat\$4 same (vacuum\$4 suction\$4))	US-PGPUB; USPAT	OR	ON	2007/04/18 16:31

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L22	0	("156" "414" "438" "29").clas. and ((transfer\$4) same (die circuit chip) same ((drop droplet) with (fluid water liquid)) same (vacuum\$4 suction\$4))	US-PGPUB; USPAT	OR	ON	2007/04/18 16:33
L23	18	("156" "414" "438" "29").clas. and ((transfer\$4) same (die circuit chip) same ((drop droplet)) same (vacuum\$4 suction\$4))	US-PGPUB; USPAT	OR	ON	2007/04/18 16:32
L24	2	("156" "414" "438" "29").clas. and ((transfer\$4) same (die circuit chip) same ((spray\$4) with (fluid water liquid)) same (vacuum\$4 suction\$4))	US-PGPUB; USPAT	OR	ON	2007/04/18 16:34
L25	31	("156" "414" "438" "29").clas. and (((vacuum\$4 suction\$4) with (die circuit chip)) same ((spray\$4) with (fluid water liquid)))	US-PGPUB; USPAT	OR	ON	2007/04/18 16:37
L26	52	("156" "414" "438" "29").clas. and (((vacuum\$4 suction\$4) with (die circuit chip)) same ((clean\$4) with (fluid water liquid)))	US-PGPUB; USPAT	OR	ON	2007/04/18 16:40
L27	716	("156" "414" "438" "29").clas. and (substrate same ((vacuum\$4 suction\$4 transfer\$4) same (die circuit chip))) and ((clean\$4 spray\$3 drop droplet) same (fluid water liquid) same substrate)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:42
L28	208	("156" "414" "438" "29").clas. and (substrate same ((vacuum\$4 suction\$4 transfer\$4) with (die circuit chip))) and ((clean\$4 spray\$3 drop droplet) with (fluid water liquid) same substrate)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:42
L29	117	("156" "414" "438" "29").clas. and (substrate same ((vacuum\$4 suction\$4 transfer\$4) with (die circuit chip))) and ((spray\$3 drop droplet) with (fluid water liquid) same substrate)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:55
L30	9	("156" "414" "438" "29").clas. and (substrate same ((vacuum\$4 suction\$4 transfer\$4) with (die circuit chip))) and (clean\$3 same (spray\$3 drop droplet) with (fluid water liquid) same substrate)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:58

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L31	175	("156" "414" "438" "29").clas. and (substrate with (die circuit chip)) and (clean\$3 same (spray\$3 drop droplet) with (fluid water liquid) same substrate)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:58
L32	31	("156" "414" "438" "29").clas. and (substrate with (die circuit chip) with (bond\$4 apply adhere\$4 adhering attach\$4)) and (clean\$3 same (spray\$3 drop droplet) with (fluid water liquid) same substrate)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:59
L33	98	("156" "414" "438" "29").clas. and ((transfer\$4) same (die circuit chip) same adhesive same (deposit\$4 coat\$4) same "over")	US-PGPUB; USPAT	OR	ON	2007/04/18 17:54
L34	14	("156" "414" "438" "29").clas. and ((transfer\$4) same (solder) same adhesive same (deposit\$4 coat\$4) same "over")	US-PGPUB; USPAT	OR	ON	2007/04/18 17:50
L35	24	("156" "414" "438" "29").clas. and ((transfer\$4) same (die circuit chip) same adhesive same (embed\$4) same "over")	US-PGPUB; USPAT	OR	ON	2007/04/18 18:28
L36	7	("156" "414" "438" "29").clas. and ((suction\$3 vacuum\$4\$4) same (die circuit chip) same adhesive same (embed\$4) same "over")	US-PGPUB; USPAT	OR	ON	2007/04/18 17:56
L37	7	("156" "414" "438" "29").clas. and ((suction\$3 vacuum\$4) same (die circuit chip) same adhesive same (embed\$4) same "over")	US-PGPUB; USPAT	OR	ON	2007/04/18 17:57
L38	86	("156" "414" "438" "29").clas. and ((suction\$3 vacuum\$4) same (die circuit chip) same adhesive same (deposit\$4 coat\$4) same "over")	US-PGPUB; USPAT	OR	ON	2007/04/18 17:57
L39	17	("3808028" "4627151" "4642321" "5030308" "5173766" "5446080" "5528157" "5536970" "5548884").PN. OR ("5904500"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 18:04

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L40	53	(US-20040252251-\$ or US-20030145939-\$ or US-20030177633-\$ or US-20050106839-\$ or US-20010001469-\$ or US-20050181597-\$ or US-20040038519-\$ or US-20040029489-\$ or US-20020013124-\$ or US-20060243205-\$ or US-20040154733-\$ or US-20030064212-\$ or US-20020170660-\$ or US-20060180595-\$ or US-20030039766-\$ or US-20070037321-\$).did. or (US-5904545-\$ or US-6919641-\$ or US-6653157-\$ or US-7182118-\$ or US-6742561-\$ or US-5591295-\$ or US-6533159-\$ or US-6059176-\$ or US-4871110-\$ or US-7033842-\$ or US-6957760-\$ or US-5911456-\$ or US-6410415-\$ or US-4452557-\$ or US-6551048-\$ or US-4556362-\$ or US-7165711-\$ or US-6193136-\$ or US-6869640-\$ or US-7101013-\$ or US-5395446-\$ or US-5804507-\$ or US-6657289-\$ or US-4471082-\$ or US-5605715-\$ or US-7182830-\$). did. or (US-7028397-\$ or US-5765277-\$ or US-6751853-\$ or US-6159767-\$ or US-6794040-\$ or US-6427325-\$ or US-6981317-\$ or US-7056767-\$ or US-6248201-\$ or US-6291271-\$ or US-5904500-\$). did.	US-PGPUB; USPAT	OR	ON	2007/04/18 18:07
L41	45	40 and (vacuum\$3 suction\$3)	US-PGPUB; USPAT	OR	ON	2007/04/18 18:07
L47	38	("156" "414" "438" "29").clas. and ((transfer\$4) same (die circuit chip) same adhesive same (anisotropic with conduct\$4))	US-PGPUB; USPAT	OR	ON	2007/04/18 18:38
L48	0	("156" "414" "438" "29").clas. and ((transfer\$4) same (pixel) same adhesive same (anisotropic with conduct\$4))	US-PGPUB; USPAT	OR	ON	2007/04/18 18:38
S1	5	("5545291" "6291896" "5545291" "6274508" "6281038" "6316278"). PN.	US-PGPUB; USPAT	OR	ON	2007/04/16 09:35
S2	2	("6731353" "6683663").PN.	US-PGPUB; USPAT	OR	ON	2007/04/16 09:57

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S3	29	("20010031514" "3349416" "4191800" "4514583" "4966442" "5034802" "5436744" "5453864" "5545291" "5824186" "5904545" "6091332" "6094138" "6246327" "6274508" "6281038" "6291896" "6316278" "6468638" "6606247").PN. OR ("6731353").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 09:35
S4	5	("5545291" "6274508" "6281038" "6316278").PN. OR ("6683663").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 09:36
S5	31	(S1 S2 S3 S4)	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 09:36
S6	1	("6927085").PN.	US-PGPUB; USPAT	OR	ON	2007/04/16 10:07
S7	1434	(56/539 156/556 156/559 156/560).ccls.	US-PGPUB; USPAT	OR	ON	2007/04/16 10:08
S8	80	S7 and (transfer\$3 same (nozzle suction\$3) same (device wafer block substrate chip))	US-PGPUB; USPAT	OR	ON	2007/04/16 10:54
S9	11	("5653575" "5765277" "6012502").PN. OR ("6742561").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 10:20
S10	0	(transfer\$3 same ((nozzle suction\$3) with (multiple plurality) with (simulatneous\$3) with (device wafer block substrate chip)))	US-PGPUB; USPAT	OR	ON	2007/04/16 10:34
S11	28	(transfer\$3 same ((nozzle suction\$3) with (multiple plurality) with (simultaneous\$3) with (device wafer block substrate chip)))	US-PGPUB; USPAT	OR	ON	2007/04/16 10:53
S12	7	("20030110610" "5695667" "5839187" "5840594" "5872051" "6759738" "6789720").PN. OR ("7033842").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 10:39
S13	38	("4332341" "4688939" "4871110" "5058178" "5088639" "5118027" "5219117" "5284287" "5445313" "5467913" "5506385" "5574801").PN. OR ("5695667").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 10:45
S14	1	"20040252251"	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 10:45

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S15	1	(transfer\$3 same ((nozzle suction\$3) with (multiple plurality) with (simultaneous\$3) with (die)))	US-PGPUB; USPAT	OR	ON	2007/04/16 10:53
S16	12	"FSA" and (transfer\$3 same (nozzle suction\$3) same (device wafer block substrate chip die circuit))	US-PGPUB; USPAT	OR	ON	2007/04/16 11:09
S17	9	("4990462" "5545291" "5783856" "5824186" "5904545" "6281038").PN. OR ("6653157"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 11:06
S18	53	"FSA" and (transfer\$3 same (function\$2) same (block))	US-PGPUB; USPAT	OR	ON	2007/04/16 11:25
S19	44	"FSA" and (transport\$3 same (function\$2) same (block))	US-PGPUB; USPAT	OR	ON	2007/04/16 13:24
S20	26	((transfer\$4 transport\$3) with (suction\$3 vacuum\$3) with (function\$2) with (block))	US-PGPUB; USPAT	OR	ON	2007/04/16 13:34
S21	1232	((transfer\$4 transport\$3) with (suction\$3 vacuum\$3) with (device chip die wafer diode "LED" circuit) with (multiple plurality))	US-PGPUB; USPAT	OR	ON	2007/04/16 13:35
S22	60	((transfer\$4 transport\$3) with (suction\$3 vacuum\$3) with (device chip die wafer diode "LED" circuit) with (multiple plurality) with (simultaneous\$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 13:58
S23	13	("3940908" "4044937" "4423815" "4556362" "4915565" "4958982" "4978253" "5394973" "5888127" "5988065" "6006890" "6019564" "6283693").PN. OR ("6551048"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 13:46
S24	18	(US-20030145939-\$ or US-20030177633-\$ or US-20040252251-\$).did. or (US-7182118-\$ or US-6742561-\$ or US-5591295-\$ or US-7033842-\$ or US-6957760-\$ or US-6533159-\$ or US-6059176-\$ or US-4871110-\$ or US-6919641-\$ or US-5904545-\$ or US-6653157-\$ or US-6551048-\$ or US-5911456-\$ or US-4452557-\$ or US-4556362-\$).did.	US-PGPUB; USPAT	OR	ON	2007/04/16 13:55
S25	15	S24 and (tape adhesive)	US-PGPUB; USPAT	OR	ON	2007/04/16 13:55

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S26	0	((invert\$4 flip\$4) with (suction\$3 vacuum\$3) with (device chip die wafer diode "LED" circuit) with (multiple plurality) with (simultaneous\$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 13:58
S27	43	((invert\$4 flip\$4) with (suction\$3 vacuum\$3) with (device chip die wafer diode "LED" circuit) with (multiple plurality))	US-PGPUB; USPAT	OR	ON	2007/04/16 14:30
S28	346	((suction\$3 vacuum\$3) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4)) and ((eject\$4 dispense\$4 coat\$4) same (liquid fluid) same (adhesive))	US-PGPUB; USPAT	OR	ON	2007/04/16 14:31
S29	61	((suction\$3 vacuum\$3) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4)) and (((eject\$4 dispense\$4 coat\$4) same (liquid fluid) same (adhesive)) same (substrate receipt\$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 14:48
S30	42	((suction\$3 vacuum\$3) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4)) and (((eject\$4 dispense\$4 coat\$4) same (liquid fluid) same (water)) same (substrate receipt\$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 15:58
S31	25	((suction\$3 vacuum\$3) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4)) and (((eject\$4 dispense\$4 coat\$4) same (drop droplets) same (water)) same (substrate receipt\$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 14:49
S32	604	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4)) and (((eject\$4 dispense\$4 coat\$4) same (liquid fluid) same (water)) same (substrate receipt\$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:19
S33	318	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4)) and (((eject\$4 dispense\$4 coat\$4) same (spray\$3 drop droplets) same (water)) same (substrate receipt\$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:19
S34	154	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4)) and (((eject\$4 dispense\$4 coat\$4 spray\$4) same (drop droplets) same (water)) same (substrate receipt\$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:21

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S35	17	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4)) and (((eject\$4 dispense\$4 coat\$4 spray\$4) with (drop droplets) with (water))) with (substrate receipt\$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:38
S36	129	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4)) and (((eject\$4 dispense\$4 coat\$4 spray\$4) with (drop droplets) with (water)))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:24
S37	283	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4)) and (((eject\$4 dispense\$4 coat\$4 spray\$4) with (drop droplets) with (liquid))) with (substrate receipt\$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:31
S38	282	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4)) and (((eject\$4 dispense\$4 coat\$4 spray\$4) with (drop droplets) with (liquid))) with (substrate))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:32
S39	14	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4) with (vacuum\$4 suction\$4)) and (((eject\$4 dispense\$4 coat\$4 spray\$4) with (drop droplets) with (liquid))) with (substrate))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:42
S40	2	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4)) and (((eject\$4 dispense\$4 coat\$4 spray\$4) with (drop droplets) with (water))) with (substrate receipt\$3) with (transport\$4 transfer\$4))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:39
S41	5	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4)) and (((eject\$4 dispense\$4 coat\$4 spray\$4) with (drop droplets) with (water))) with (substrate receipt\$3)) same (transport\$4 transfer\$4))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:38

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S42	156	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4)) and (((eject\$4 dispense\$4 coat\$4 spray\$4) with (drop droplets) with (liquid fluid)) with (substrate recept\$3) with (transport\$4 transfer\$4))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:39
S43	1	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4) with (vacuum\$4 suction\$4)) and (((eject\$4 dispense\$4 coat\$4 spray\$4) with (drop droplets) with (fluid)) with (substrate))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:47
S44	25	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4) with (vacuum\$4 suction\$4)) and ((eject\$4 dispense\$4 coat\$4 spray\$4) with (drop droplets) with (substrate))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:52
S45	4	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4) with (vacuum\$4 suction\$4)) and ((water) with (drop droplets) with (substrate))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:52
S46	38	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer\$4 transport\$4) with (vacuum\$4 suction\$4)) and ((liquid) with (drop droplets) with (substrate))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:53
S47	4	((transfer\$4 transport\$3) with (suction\$3 vacuum\$3) with (circuit chip device die wafer device) with (substrate)) and (substrate with (drop droplet) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:10
S48	20	((transfer\$4 transport\$3) with (suction\$3 vacuum\$3) with (circuit chip device die wafer device) with (substrate)) and (substrate with (drop droplet spray\$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:13
S49	109	((transfer\$4 transport\$3) same (suction\$3 vacuum\$3) same (circuit chip device die wafer device) same (substrate)) and (substrate with (drop droplet spray\$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:24
S50	89	S49 not S48	US-PGPUB; USPAT	OR	ON	2007/04/17 08:13

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S51	18	"156".clas. and ((transfer\$4 transport\$3) with (circuit chip device die wafer device) with (substrate)) and (substrate with (drop droplet spray\$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:59
S52	13	"FSA" and (substrate with (drop droplet spray\$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:40
S53	3	"fluidic self-assembly" and (substrate with (drop droplet spray\$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:41
S54	1802	(fluid\$3 with self-assembly) and (substrate with (drop droplet spray\$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:42
S55	3	(fluid\$3 with self-assembly) and (substrate with (drop droplet spray\$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:42
S56	5	(fluid\$3 with self with assembl\$3) and (substrate with (drop droplet spray\$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:42
S57	215	(fluid\$3 with self with assembl\$3) and (substrate with (drop droplet spray\$3 water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:43
S58	123	(fluid\$3 with self with assembl\$3) and (substrate with (drop droplet spray\$3))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:45
S59	8	(fluid\$3 with self with assembl\$3) and ((substrate with (drop droplet spray\$3)) same water)	US-PGPUB; USPAT	OR	ON	2007/04/17 10:17
S60	21	(fluid\$3 with self with assembl\$3) and ((substrate with (micro-drop\$3 eject\$3 dispens\$3)) same water)	US-PGPUB; USPAT	OR	ON	2007/04/17 08:52
S61	9	(fluid\$3 with self with assembl\$3) and ((receptor with (micro-drop\$3 eject\$3 dispens\$3)) same water)	US-PGPUB; USPAT	OR	ON	2007/04/17 08:56
S62	2	(fluid\$3 with self with assembl\$3) and ((receptor with (spray\$3 drop\$3)) same water)	US-PGPUB; USPAT	OR	ON	2007/04/17 08:56
S63	10	"156".clas. and ((transfer\$4 transport\$3) with (circuit chip device die wafer device) with (substrate)) and (substrate with (eject\$3 dispens\$3 micro-drop\$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:58
S64	233	"156".clas. and ((transfer\$4 transport\$3) with (circuit chip device die wafer device)) and ((spray\$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 09:27

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S65	16	"156".clas. and ((transfer\$4) with (circuit chip device die wafer device)) and ((spray\$3) with (water) with substrate)	US-PGPUB; USPAT	OR	ON	2007/04/17 09:30
S66	18	"156".clas. and ((transfer\$4) with (circuit chip device die wafer device)) and ((spray\$3) with (clean\$3) with substrate)	US-PGPUB; USPAT	OR	ON	2007/04/17 09:31
S67	7	"156".clas. and ((transfer\$4) with (circuit chip device die wafer device)) and ((spray\$3) with (rins\$3) with substrate)	US-PGPUB; USPAT	OR	ON	2007/04/17 09:32
S68	52	"156".clas. and ((transfer\$4) with (circuit chip device die wafer device)) and ((spray\$3) with (fluid solvent liquid) with substrate)	US-PGPUB; USPAT	OR	ON	2007/04/17 09:36
S69	20	"156".clas. and ((transfer\$4) same (suction\$3 vacuum\$3) same (circuit chip device die wafer device) same substrate) and ((spray\$3) same (fluid solvent liquid water) same substrate)	US-PGPUB; USPAT	OR	ON	2007/04/17 09:38
S70	54	("29" "438" "414").clas. and ((transfer\$4) same (suction\$3 vacuum\$3) same (circuit chip device die wafer device) same substrate) and ((spray\$3) same (fluid solvent liquid water) same substrate)	US-PGPUB; USPAT	OR	ON	2007/04/17 09:48
S71	372	((transfer\$4) same (circuit chip diode "LED" die wafer device) same substrate) and ((spray\$3) same (fluid solvent liquid water) same substrate same (before prior))	US-PGPUB; USPAT	OR	ON	2007/04/17 09:51
S72	65	("156" "414" "438" "29").clas. and ((transfer\$4) same (circuit chip diode "LED" die wafer device) same substrate) and ((spray\$3) same (fluid solvent liquid water) same substrate same (before prior))	US-PGPUB; USPAT	OR	ON	2007/04/17 10:00
S73	27	("156" "414" "438" "29").clas. and ((transfer\$4) same (circuit chip diode "LED" die wafer device)) and ((spray\$3) same (fluid solvent liquid water) same substrate same (before prior) same transfer\$4)	US-PGPUB; USPAT	OR	ON	2007/04/17 10:06

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S74	21	("156" "414" "438" "29").clas. and ((transfer\$4) same (circuit chip diode "LED" die device semiconductor)) and ((spray\$3) same (fluid solvent liquid water) same substrate same (before prior) same transfer\$4)	US-PGPUB; USPAT	OR	ON	2007/04/17 10:11
S75	10	("156" "414" "438" "29").clas. and ((transfer\$4)) and ((spray\$3) same (fluid solvent liquid water) same substrate same (before prior) same transfer\$4) not S73	US-PGPUB; USPAT	OR	ON	2007/04/18 13:52
S76	176	("156" "414" "438" "29").clas. and ((transfer\$4)) and ((spray\$3) same (fluid solvent liquid water) same substrate same transfer\$4) not S73	US-PGPUB; USPAT	OR	ON	2007/04/17 10:14
S77	176	("156" "414" "438" "29").clas. and ((spray\$3) same (fluid solvent liquid water) same substrate same transfer\$4) not S73	US-PGPUB; USPAT	OR	ON	2007/04/17 10:39
S78	268	(fluid\$3 with self with assembl\$3) and (((drop droplet spray\$3)) same water)	US-PGPUB; USPAT	OR	ON	2007/04/17 10:17
S79	46	("156" "414" "438" "29").clas. and ((spray\$3) same (fluid solvent liquid water) same substrate same transfer\$4 same (clean\$3 rins\$3))	US-PGPUB; USPAT	OR	ON	2007/04/17 10:46
S80	102	((function\$3 near3 block) diode "LED" pixel sensor) and ((spray\$3) same (fluid solvent liquid water) same substrate same transfer\$4 same (clean\$3 rins\$3))	US-PGPUB; USPAT	OR	ON	2007/04/17 10:49
S81	72	transfer\$4.ab. and ((spray\$3) same (fluid solvent liquid water) same substrate same transfer\$4 same (clean\$3 rins\$3))	US-PGPUB; USPAT	OR	ON	2007/04/17 10:54
S82	8	electronic.ab. and ((spray\$3) same (fluid solvent liquid water) same substrate same transfer\$4 same (clean\$3 rins\$3))	US-PGPUB; USPAT	OR	ON	2007/04/17 10:55
S83	129	((spray\$3) with (fluid solvent liquid water) with substrate) same transfer\$4 same (clean\$3 rins\$3))	US-PGPUB; USPAT	OR	ON	2007/04/17 11:01
S84	37	((spray\$3) with (fluid solvent liquid water) with substrate) same adhesive same (clean\$3 rins\$3))	US-PGPUB; USPAT	OR	ON	2007/04/17 11:05
S85	268	((spray\$3) with (fluid solvent liquid water) with substrate) with (clean\$3 rins\$3)) and adhesive	US-PGPUB; USPAT	OR	ON	2007/04/17 11:06

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S86	141	(((\$spray\$3) with (fluid solvent liquid water) with substrate) with (clean\$3 rins\$3)) and (adhesive same (transfer\$3 adher\$3 bond\$3))	US-PGPUB; USPAT	OR	ON	2007/04/17 11:06
S87	11	("5653575" "5765277" "6012502").PN. OR ("6742561"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 08:41
S88	26	("3604108" "5197650" "5516026" "5579980").PN. OR ("5765277"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 13:26